



Product Summary

V _{(BR)DSS}	R _{DS(on) max}	I _D T _A = 25°C		
20V	18mΩ @ V_{GS} = 4.5V	5.2A		
	$30 \mathrm{m}\Omega @ \mathrm{V}_{\mathrm{GS}} = 1.8 \mathrm{V}$	4.0A		

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

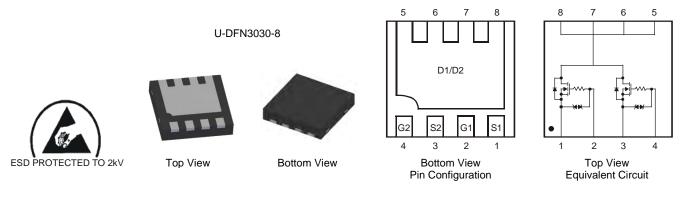
- Power management functions
- **Battery Pack**
- Load Switch

Features and Benefits

- Low On-Resistance •
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Lead, Halogen, and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: U-DFN3030-8 .
- Case Material: Molded Plastic, "Green" Molding Compound. UL • Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.0172 grams (approximate)



Ordering Information (Note 6)

Part Number	Case	Packaging
DMN2016LFG-7	U-DFN3030-8	3000 / Tape & Reel

1. No purposefully added lead. Halogen and Antimony Free.

Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
For packaging details, go to our website at http://www.diodes.com

Marking Information

Notes:



N20 = Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 09 for 2009) WW = Week code (01 to 53)



Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 4)	Steady State	T _A = 25°C T _A = 70°C	ID	5.2 4.1	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	PD	0.77	W
Thermal Resistance, Junction to Ambient $@T_A = 25^{\circ}C$ (Note 4)	R _{θJA}	169	°C/W
Thermal Resistance, Junction to Case $@T_A = 25^{\circ}C$ (Note 4)	R _{θJC}	15.8	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

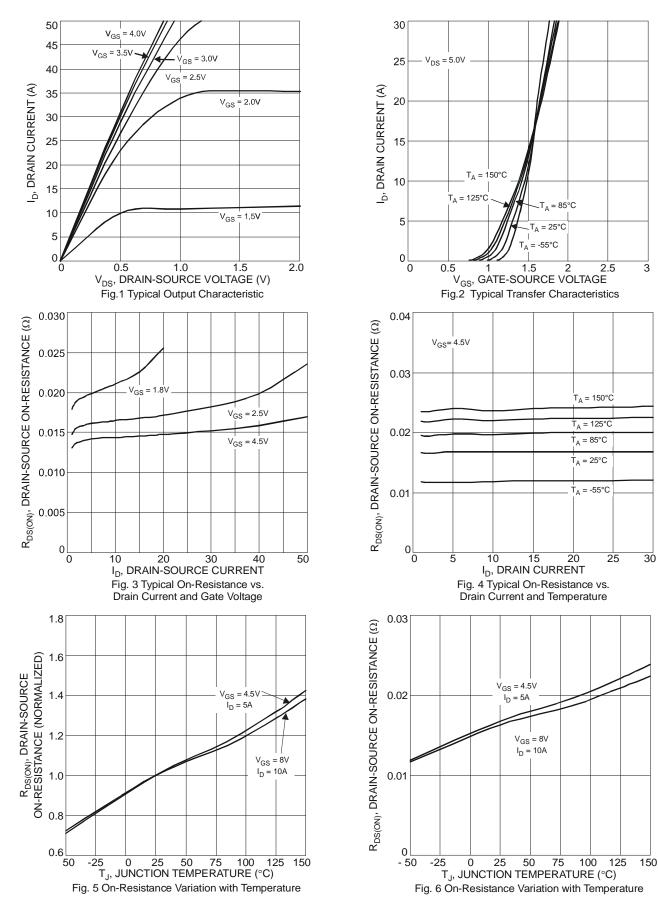
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Gate-Source Breakdown Voltage	BV _{GSO}	±8	-	-	V	$V_{DS} = 0V, I_G = \pm 250 \mu A$	
Zero Gate Voltage Drain Current TJ = 25°C	IDSS	-	-	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V _{GS(th)}	0.4	0.71	1.1	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
			13	18	mΩ	$V_{GS} = 4.5V, I_D = 6A$	
			13.5	19		$V_{GS} = 4.0V, I_D = 6A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	-	14	20.5		$V_{GS} = 3.1V, I_D = 6A$	
			15	22		$V_{GS} = 2.5V, I_D = 6A$	
			21	30		$V_{GS} = 1.8V, I_D = 6A$	
Forward Transfer Admittance	Y _{fs}	-	25	-	S	$V_{DS} = 5V, I_D = 6A$	
Diode Forward Voltage	V _{SD}	-	0.75	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	Ciss	-	1472	-	pF		
Output Capacitance	Coss	-	311	-	pF	−V _{DS} = 10V, V _{GS} = 0V, −f = 1.0MHz	
Reverse Transfer Capacitance	Crss	-	141	-	pF	1 = 1.000112	
Gate Resistance	Rg	-	1.46	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	-	16.0	-	nC		
Gate-Source Charge	Q _{gs}	-	36.6	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$	
Gate-Drain Charge	Q _{gd}	-	2.1	-	nC	$-I_D = 6A$	
Turn-On Delay Time	t _{D(on)}	-	2.6	-	ns		
Turn-On Rise Time	tr	-	13.2	-	ns	$V_{DD} = 10V, V_{GS} = 5V,$	
Turn-Off Delay Time	t _{D(off)}	-	84.5	-	ns	$R_{GEN} = 3\Omega, R_L = 1.7\Omega$	
Turn-Off Fall Time	tf	-	46.8	-	ns]	

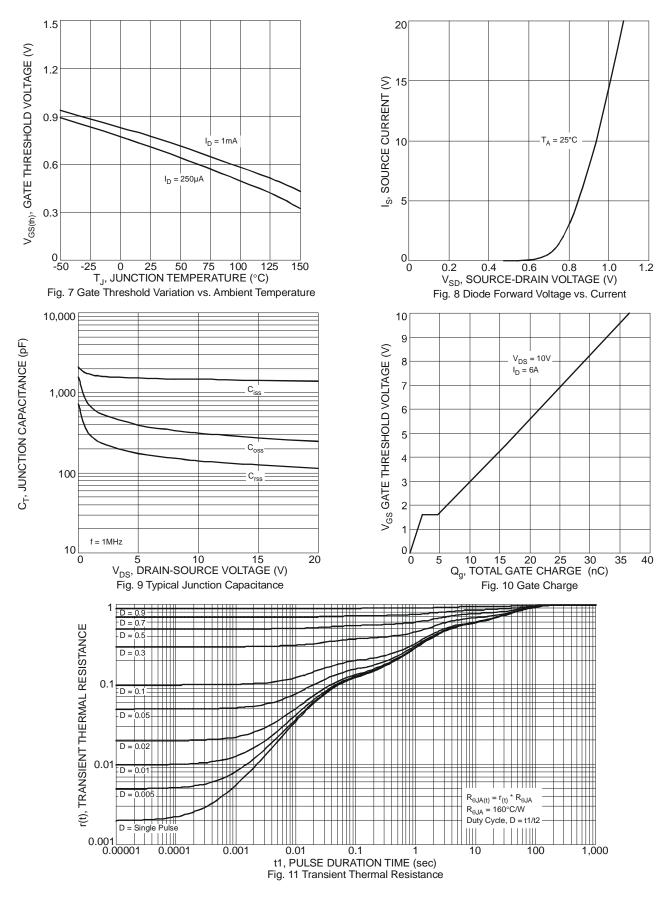
 Device mounted on FR-4 PCB, with minimum recommended pad layout.
Repetitive rating, pulse width limited by junction temperature
Guaranteed by design. Not subject to product testing Notes:



DMN2016LFG

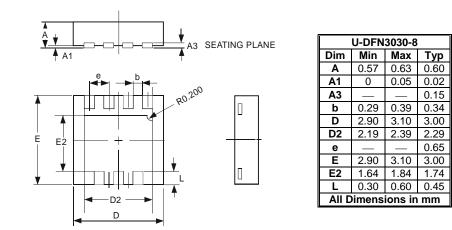




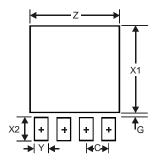




Package Outline Dimensions



Suggested Pad Layout



Dimensions	Value (in mm)				
Z	2.59				
G	0.11				
X1	2.49				
X2	0.65				
Y	0.39				
С	0.65				



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